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PATENT  
YOR920030206US1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of : Larry Shungwei Mok  
Serial Number : 10/784,624  
Filing Date : February 23, 2004  
Examiner : Tho V. Duong  
Group Art Unit : 3753  
For : HEAT DISSIPATION INTERFACE FOR  
SEMICONDUCTOR STRUCTURES

TO: The Honorable Commissioner of Patents  
and Trademarks  
Post Office Box 1450  
Alexandria, VA 22313-1450

**CHANGE OF ADDRESS**

Please address all future correspondence in this application to the undersigned as attorney of record at 6136 West Kimberly Way, Glendale, AZ 85308.

Respectfully Submitted,

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I hereby certify that this paper is being transmitted via the United States Postal Service, in a sealed envelope, postage prepaid, on the date indicated below, addressed to Commissioner of Patents & Trademarks, Post Office Box 1450, Alexandria, VA 22313-1450

Signature:

Name:

*Thomas A. Beck*  
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Date: June 14, 2007